

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.47576	100.0	25.56
			<b>Subtotal</b>	<b>0.47576</b>	<b>100</b>	<b>25.56</b>
Lead Frame		Phosphorous (P)	7723-14-0	0.0188	0.03	1.00983
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.67668	1.08	36.35388
		Copper (Cu)	7440-50-8	61.95984	98.89	3,328.73629
			<b>Subtotal</b>	<b>62.65532</b>	<b>100</b>	<b>NaN</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.65911	7.7	142.8581
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.14406	12.0	222.636
	Filler	Silica fused	60676-86-0	27.62708	80.0	1,484.24
	Carbon Black	Carbon black	1333-86-4	0.1036	0.3	5.5659
			<b>Subtotal</b>	<b>34.53385</b>	<b>100</b>	<b>NaN</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.78132	100.0	95.7
			<b>Subtotal</b>	<b>1.78132</b>	<b>100</b>	<b>95.7</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.26002	100.0	13.96932
			<b>Subtotal</b>	<b>0.26002</b>	<b>100</b>	<b>13.96932</b>
Solder Wire	Pure metal	Tin (Sn)	7440-31-5	0.01469	5.0	0.789
	Pure metal	Silver (Ag)	7440-22-4	0.00441	1.5	0.2367
	Pure metal	Lead (Pb)	7439-92-1	0.27463	93.5	14.7543
			<b>Subtotal</b>	<b>0.29373</b>	<b>100</b>	<b>15.78</b>
			<b>Total</b>	<b>100</b>	<b>100</b>	<b>NaN</b>

#### Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.